

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/B/PTO				Complete If Known	
				Application Number	10/766,629 (Conf. No. 3771)
				Filing Date	January 27, 2004
				First Named Inventor	Glenn J. Leedy
				Art Unit	2818
				Examiner Name	Thinh T. Nguyen
Sheet	1	of	1	Attorney Docket Number	ELM-1 Cont.15

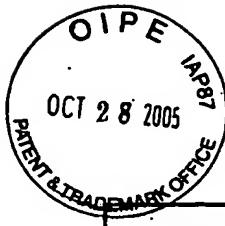
U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)			
TJL		US 3,932,932	01-20-1976	Goodman	
		US 4,028,547	06-07-1977	Eisenberger	
		US 4,393,127	07-12-1983	Greschner et al.	
		US 4,528,072	07-09-1985	Kurosawa et al.	
		US 4,810,889	03-07-1989	Yokomatsu et al.	
		US 5,051,326	09-24-1991	Celler et al.	
		US 5,166,962	11-24-1992	Murooka et al.	
		US 5,169,805	12-08-1992	Mok et al.	
		US 5,188,706	02-23-1993	Hori et al.	
		US 5,432,999	07-18-1995	Capps et al.	
		US 5,577,050	11-19-1996	Bair et al.	
		US 5,745,673	04-28-1998	Di Zenzo et al.	
TJL		US 5,818,748	10-06-1998	Bertin et al.	

FOREIGN PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)			

NON PATENT LITERATURE DOCUMENTS					
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.			

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹Applicant's unique citation designation number (optional). ²See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 801.04. ³Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶Applicant is to place a check mark here if English language Translation is attached.

Examiner Signature	TJL - TJL + (O	Date Considered	April 2006
--------------------	----------------	-----------------	------------



Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

PTO/SB/08a/b (08-03)

Approved for use through 07/31/2006. OMB 0651-0031
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Substitute for form 1449A/B/PTO				Complete If Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Application Number	10/766,629 (Conf. No. 3771)
(Use as many sheets as necessary)				Filing Date	January 27, 2004
				First Named Inventor	Glenn J. Leedy
				Art Unit	2818
				Examiner Name	Thinh T. Nguyen
Sheet	1	of	3	Attorney Docket Number	ELM-1 Cont.15

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)			
TH		US 4,604,162	08-05-1986	Sobczak	
		US 4,849,857	07-18-1989	Butt et al.	
		US 4,928,058	05-22-1990	Williamson	
		US 4,990,462	02-05-1991	Sliwa	
		US 5,110,712	05-05-1992	Kessler et al.	
		US 5,119,164	06-02-1992	Sliwa et al.	
		US 5,284,804	02-08-1994	Moslehi	
		US 5,480,842	01-02-1996	Clifton et al.	
		US 5,470,693	11-28-1995	Sachdev et al.	
		US 5,733,814	03-31-1998	Flesher et al.	
TH		US Re 37,637	04-09-2002	Clifton et al.	

FOREIGN PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)			
TH		EP 0 201 380 B1	12-17-1986	Fairchild Semiconductor Corporation	
		EP 0 224 418 B1	06-03-1987	Fujitsu Limited	
		EP 0 419 898 B1	04-03-1991	Siemens Aktiengesellschaft	
		EP 0 455 455 B1	11-06-1991	AT&T Corp.	
		EP 0 487 302 B1	05-27-1992	Shin-ETSU Handotai Company Limited	
		EP 0 503 816 B1	09-16-1992	Shin-ETSU Handotai Company Limited	
		EP 0 518 774 B1	12-16-1992	France Telecom	
		EP 0 526 551 B1	02-10-1993	The Commonwealth of Australia	
		EP 0 554 063 B1	08-04-1993	Canon Kabushiki Kaisha	
		EP 0 555 252 B1	08-18-1993	Fraunhofer-Gesellschaft Zur Förderung Der Angewandten Forschung E.V..	
		WO 1989 010255	11-02-1989	3D Systems Inc.	
		WO 1990 009093	08-23-1990	Polylithics Inc.	
TH		WO 1992 017901	10-15-1992	Integrated System Assemblies Corporation	

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

Examiner Signature	TH - TH - HC	Date Considered	April 2006
--------------------	--------------	-----------------	------------

Substitute for form 1449A/B/PTO				Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>				Application Number	10/766,629 (Conf. No. 3771)
Sheet	2	of	3	Filing Date	January 27, 2004
				First Named Inventor	Glenn J. Leedy
				Art Unit	2818
				Examiner Name	Thinh T. Nguyen
				Attorney Docket Number	ELM-1 Cont.15

NON PATENT LITERATURE DOCUMENTS					
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.			
TJL		Jones, R.E., Jr. "An evaluation of methods for passivating silicon integrated circuits"; April 1972; pp. 23-8			T ²
		Svechnikov, S.V.; Kobylavskaya, M.F.; Kimarskii, V.I.; Kaufman, A.P.; Kuzovlev, Yu. I.; Cherepov, Ye. I.; Fomin, B.I.; "A switching plate with aluminum membrane crossings of conductors"; 1972			
		Sun, R.C.; Tisone, T.C.; Cruzan, P.D.; "Internal stresses and resistivity of low-voltage sputtered tungsten films (microelectronic cct. conductor)"; March 1973; pp. 1009-16			
		Wade, T.E.; "Low temperature double-exposed polyimide/oxide dielectric for VLSI multilevel metal interconnection"; 1982; pp. 516-19			
		Boyer, P.K.; Collins, G.J.; Moore, C.A.; Ritchie, W.K.; Roche, G. A.; Solanski, R. (A); Tang, C.C.; "Microelectronic thin film deposition by ultraviolet laser photolysis MONOGRAPH TITLE - Laser processing of semiconductor devices"; 1983; pp. 120-126			
		Boyer, P.K.; Moore, C.A.; Solanki, R.; Ritchie, W.K.; Roche, G.A.; Collins, G.J.; "Laser photolytic deposition of thin films"; 1983; pp. 119-27			
		Chen, Y.S.; Fatemi, H.; "Stress measurements on multilevel thin film dielectric layers used in Si integrated circuits"; May-June 1986; pp. 645-9			
		Salazar, M.; Wilkins, C.W., Jr.; Ryan, V.W.; Wang, T.T.; "Low stress films of cyclized polybutadiene dielectrics by vacuum annealing"; Oct. 21-22, 1986; pp. 96-102			
		Townsend, P.H.; Huggins, R.A.; "Stresses in borophosphosilicate glass films during thermal cycling"; Oct. 21-22, 1986; pp. 134-41			
		Pai, Pei-Lin; "Multilevel Interconnection Technologies--A Framework And Examples"; 1987; pp. 1871			
		Pei-lin Pai; Chetty, A.; Roat, R.; Cox, N.; Chiu Ting; "Material characteristics of spin-on glasses for interlayer dielectric applications"; November 1987, pp. 2829-34			
		Allen, Mark G.; Senturia, Stephen D.; "Measurement of polyimide interlayer adhesion using microfabricated structures"; 1988; pp. 352-356			
		Chang, E.Y.; Cibuzar, G.T.; Pande, K.P.; "Passivation of GaAs FET's with PECVD silicon nitride films of different stress states"; September 1988; pp. 1412-18			
		Riley, P.E.; Shelley, A.; "Characterization of a spin-applied dielectric for use in multilevel metallization"; May 1988; pp. 1207-10			
		Tamura, H.; Nishikawa, T.; Wakino, K.; Sudo, T.; "Metalized MIC substrates using high K dielectric resonator materials"; October 1988; pp. 117-126			
		Kochugova, I.V.; Nikolaeva, L.V.; Vakser, N.M., (M.I. Kalinin Leningrad Polytechnic Institute (USSR); "Electrophysical investigation of thin-layered inorganic coatings"; 1989; pp. 826-828			
TJL		Roche, J.J. H.; "Control of thin film materials properties used in high density multichip interconnect"; April 24-28, 1989; p. 494			

Examiner Signature	TJL - TJL + HO	Date Considered	April 12 2006
--------------------	----------------	-----------------	---------------

Substitute for form 1449A/B/PTO				Complete If Known	
				Application Number	10/766,629 (Conf. No. 3771)
				Filing Date	January 27, 2004
				First Named Inventor	Glenn J. Leedy
				Art Unit	2818
				Examiner Name	Thinh T. Nguyen
Sheet	3	of	3	Attorney Docket Number	ELM-1 Cont.15

NON PATENT LITERATURE DOCUMENTS					
Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.			²
TH		Maw, T.; Hopla, R.E.; "Properties of a photoimageable thin polyimide film"; Nov. 26-29-, 1990; pp. 71-6			
TH		Draper, B. L.; Hill, T.A.; "Stress and stress relaxation in integrated circuit metals and dielectrics"; July-Aug. 1991; pp. 1956-62			
TH		Guckel, H.; "Surface micromachined pressure transducers"; 1991; pp. 133-146			
TH		Garino, T.J.; Harrington, H. M.; "Residual stress in PZT thin films and its effect on ferroelectric properties"; 1992; pp. 341-7			

¹EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

²Applicant's unique citation designation number (optional). ²Applicant is to place a check mark here if English language Translation is attached.

Examiner Signature	The TH	Date Considered	Apr 1 2006
--------------------	--------	-----------------	------------